

# HIGH-SPEED BICMOS ECL STATIC RAM 64K (16K x 4-BIT) with SYNCHRONOUS WRITE

ADVANCE INFORMATION IDT10497 IDT100497 IDT101497

#### **FEATURES:**

- · 16,384-words x 4-bit organization
- Address access time: 12/15 ns
- · Read Data output latch for extended hold time
- · Short Write Cycle input data and address valid time
- Pin compatible with standard 16K x 4
- · Through-hole DIP and surface-mount packages

### **DESCRIPTION:**

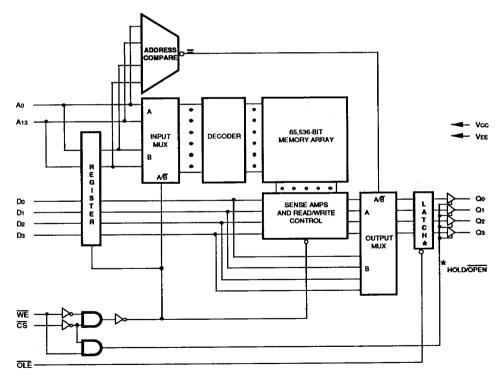
The IDT10497, IDT100497 and IDT101497 are 65,536-bit high-speed BiCEMOS™ ECL static random access memories organized as 16K x 4, with inputs and outputs fully compatible with ECL levels. Internal registers on inputs

provide enhanced Write Cycle performance over conventional RAMs, while output read data latch allows longer output data hold time providing easier design and improved system level cycle times.

In the read mode, this device is pinout and timing compatible with the standard asynchronous SRAMs (IDT10494), yet the addition of an output latch with separate enable control allow output data to be captured and held long into the next cycle. This minimizes noise on the data bus and provides better set-up time margin for the next logic stage in pipelined applications.

In the write mode, the device adds an invisible pipeline stage in the write address and data paths, allowing very short set-up and hold times for these inputs and less stringent requirements for the write pulse input.

#### **FUNCTIONAL BLOCK DIAGRAM**



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**COMMERCIAL TEMPERATURE RANGE** 

AUGUST 1990

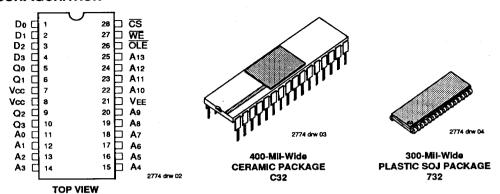
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### PIN CONFIGURATION



#### PIN DESCRIPTIONS

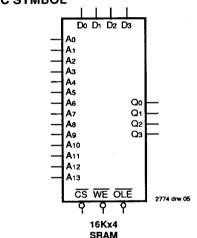
Symbol	Pin Name
Ao through A13	Address Inputs
Do through Ds	Data Inputs
Qo through Qs	Data Outputs
WE	Write Enable Input
<del>CS</del>	Chip Select Input (Internal pull down)
OLE	Output Latch Enable
VEE	More Negative Supply Voltage
Vcc	Less Negative Supply Voltage
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# AC OPERATING RANGES(1)

1/0	VEE	Temperature
10K	-5.2V ±5%	0 TO 75°C, air flow exceeding 2 m/sec
100K	-4.5V ±5%	0 TO 85°C, air flow exceeding 2 m/sec
101K	-4.75V to -5.46V	0 TO 75°C, air flow exceeding 2 m/sec
101K	-4.75V to -5.46V	0 TO 75°C, air flow exceeding

<sup>1.</sup> Referenced to Vcc

# LOGIC SYMBOL



CAPACITANCE (TA=+25°C, f=1.0MHz)

CIN         Input Capacitance         4         -         3         -         p           COUT         Output         6         -         3         -         p			DIP		S		
Cout Output 6 - 3 - p	Symbol	Parameter	Тур.	Max.	Тур.	Max.	Unit
	CIN		4	-	3	-	pF
Capacitance	Cout	Output Capacitance	6	-	3	_	pF

TRUTH TABLE(1)

CS	WE	OLE	DataouT <sup>(2)</sup>	Function
Н	X	Х	L	Deselected
L	Н	L	RAM Data	Read
L	Н	Н	RAM Data	Output Held
L	L	Х	L	Write
				2774 th

NOTES:

1. H=High, L=Low, X=Don't Care

2. DATAOUT initiated by falling edge of OLE.

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# **ECL-10K ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

Symbol	Ratir	ng	Value	Unit
VTERM	Terminal Voltage With Respect to GND		+0.5 to -7.0	٧
TA	Operating Temp	perature	0 to +75	°C
TBIAS	Temperature U	nder Bias	-55 to +125	°C
Тѕтс	Storage Ceramic Temperature Plastic		-65 to +150 -55 to +125	°C
Рт	Power Dissipati	on	2.0	W
lout	DC Output Current (Output High)		-50	mA

NOTE:

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# **ECL-10K DC ELECTRICAL CHARACTERISTICS**

(VEE = -5.2V, RL =50 $\Omega$  to -2.0V, TA = 0 to +75°C, air flow exceeding 2 m/sec)

Output HIGH Voltage Output LOW Voltage Output Threshold HIGH Voltage			-1000 -960 -900 -1870 -1850 -1830	-885	-840 -810 -720 -1665	mV mV	0°C 25°C 75°C 0°C
		VILB	-1850	_		mV	
Output Threshold HIGH Voltage	V IN = V IHB OI	VIN = VIHA or VILB			-1650 -1625		25°C 75°C
	VIN = VIHB or VILA		-1020 -980 -920	_	_	mV	0°C 25°C 75°C
Output Threshold LOW Voltage	V IN = V IHB OF V ILA		_	<del>-</del>	-1645 -1630 -1605	mV	0°C 25°C 75°C
Input HIGH Voltage	Guaranteed Input Voltage High for All Inputs		-1145 -1105 -1045	-	-840 -810 -720	mV	0°C 25°C 75°C
Input LOW Voltage	Guaranteed Input Voltage Low for All Inputs		-1870 -1850 -1830	_	-1490 -1475 -1450	mV	0°C 25°C 75°C
Input HIGH Current	V IN = V IHA CS Others		-	_	220	μА	<u> </u>
·			_	_	110	μΑ	
Input LOW Current	V IN = V ILB	CS	0.5	-	170	μΑ	_
•		Others	-50	_	90	μΑ	<u> </u>
Supply Current	All Inputs and Outputs Open		-260	-200	-	mA	-
	Input HIGH Voltage Input LOW Voltage Input HIGH Current Input LOW Current	Input HIGH Voltage  Guaranteed In High for All In Cow for All In C	Input HIGH Voltage  Guaranteed Input Voltage High for All Inputs  Guaranteed Input Voltage Low for All Input Voltage Low for All Input Voltage V IN = V IHA  CS Others  Input LOW Current  V IN = V ILB  CS Others	Comput HIGH Voltage	Comput HIGH Voltage	-   -   -   -   -   -   -   -   -   -	The state of th

NOTES:

<sup>1.</sup> Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

<sup>1.</sup> Typical parameters are specified at VEE = -5.2V, Ta = +25°C and maximum loading.

## ECL-100K ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Ratin	Value	Unit	
VTERM	Terminal Voltage With Respect to	+0.5 to -7.0	٧	
TA	Operating Tempe	0 to + 85	°C	
TBIAS	Temperature Und	-55 to +125	°C	
Тѕтс	Storage Ceramic Temperature		-65 to +150	°C
Рт	Power Dissipatio	n	1.0	W
lout	DC Output Current (Output High)		-50	mA

NOTE:

#### **ECL-100K DC ELECTRICAL CHARACTERISTICS**

(VEE = -4.5V, RL =50 $\Omega$  to -2.0V, TA = 0 to +85°C, air flow exceeding 2 m/sec)

Symbol	Parameter	Test C	onditions	Min. (B)	Typ. <sup>(1)</sup>	Max. (A)	Unit
Vон	Output HIGH Voltage	V IN = V IHA O	r V ILB	-1025	-955	-880	mV
Vol	Output LOW Voltage	V IN = V IHA or V ILB		-1810	-1715	-1620	m۷
Vонс	Output Threshold HIGH Voltage	V IN = V IHB or V ILA		-1035	-	-	mV
Volc	Output Threshold LOW Voltage	V IN = V IHB o	V IN = V IHB OF V ILA		-	-1610	mV
ViH	Input HIGH Voltage	Guaranteed Input Voltage High for All Inputs		-1165	-	-880	mV
VIL	Input LOW Voltage	Guaranteed Input Voltage Low for All Inputs		-1810	-	-1475	mV
l IH	Input HIGH Current	V IN = V IHA	cs	_	-	220	μА
			Others	_	_	110	1
l IL	Input LOW Current	V IN = V ILB	CS	0.5	-	170	μА
		1	Others	-50	_	90	1
lee	Supply Current	All Inputs and Outputs Open		-240	-180	_	mA
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NOTE:

<sup>1.</sup> Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

<sup>1.</sup> Typical parameters are specified at VEE = -4.5V, TA = +25°C and maximum loading.

# **ECL-101K ABSOLUTE MAXIMUM RATINGS**(1)

Symbol	Ratir	ng	Value	Unit
VTERM	Terminal Voltag With Respect to	+0.5 to -7.0	٧	
TA	Operating Temp	perature	0 to +75	°C
TBIAS	Temperature U	nder Bias	-55 to +125	°C
<b>T</b> STG	Storage Ceramic Plastic		-65 to +150 -55 to +125	°C
Рт	Power Dissipat	ion	2.0	W
lout	DC Output Current (Output High)		-50	mA

## **ECL-101K DC ELECTRICAL CHARACTERISTICS**

(VEE = -5.2V, RL =50 $\Omega$  to -2.0V, TA = 0 to +75°C, air flow exceeding 2 m/sec)

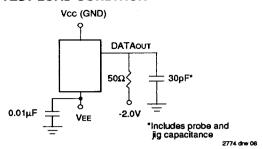
Symbol	Parameter	Test C	Condition	Min. (B)	Typ. <sup>(1)</sup>	Max. (A)	Unit
Voн	Output HIGH Voltage	V IN = V IHA OF V ILB		-1025	-955	-880	mV
Vol.	Output LOW Voltage	V IN = V IHA or V ILB		-1810	-1715	-1620	mV
Vohc	Output Threshold HIGH Voltage	V IN = V IHB or V ILA		-1035	-	_	mV
Volc	Output Threshold LOW Voltage	V IN = V IHB or V ILA				-1610	mV
ViH	Input HIGH Voltage	Guaranteed Input Voltage High for All Inputs		-1165	-	-880	mV
VaL	Input LOW Voltage	Guaranteed Input Voltage Low for All Inputs		-1810	_	-1475	mV
Lін	Input HIGH Current	V IN = V IHA CS		_	_	220	μА
		İ	Others	_	_	110	
I IL	Input LOW Current	V IN = V ILB	<u>CS</u>	0.5		170	μΑ
	<u> </u>	Others		-50	-	90	1
IEE	Supply Current	All Inputs and Outputs Open		-260	-200	_	mA
0.75	1	<del></del>				*	2774 t

NOTE:

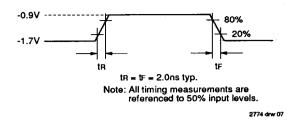
NOTE: 1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

<sup>1.</sup> Typical parameters are specified at VEE = -5.2V, TA = +25°C and maximum loading.

#### AC TEST LOAD CONDITION



#### **AC TEST INPUT PULSE**



#### RISE/FALL TIME

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
t <sub>R</sub>	Output Rise Time	_	_	2	_	ns
t <del>r</del>	Output Fall Time	_	T -	2		nş
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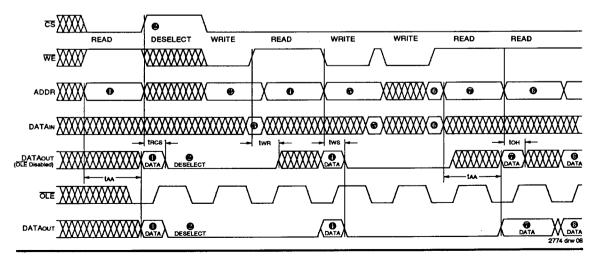
#### **FUNCTIONAL DESCRIPTION**

The IDT10497. IDT100497, and IDT101497 BiCMOS ECL static RAMs (SRAM) with SYNCHRONOUS WRITE provide high speed with low power dissipation typical of BiCMOS ECL. On-chip logic additionally helps improve system performance, yet the device is pinout-compatible with asynchronous equivalents (i.e... IDT10494, IDT100494, and IDT101494 respectively). The ECL-101K meets electrical specifications that combine the ECL-100K temperature and voltage compensated output levels with the high-speed of ECL-10K VEE compatibility (-5.2V).

As can be seen in the Functional Block Diagram on the title page, this device contains clocked input registers to sample and hold addresses and input data, during a write cycle only. Inputs are sampled on the rising edge of the Write Enable ( $\overline{WE}$ ). The write cycle is pipelined: the memory cell is written during the  $\overline{WE}$ -low time in the next cycle.

Read cycles are not pipelined and operate identically to an asynchronous device, except that an output latch is provided to capture and hold Read data.

#### **FUNCTIONAL DESCRIPTION TIMING EXAMPLE**



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#### **READ TIMING**

The read timing on the device is asynchronous. Dataout is held low until the device is selected by Chip Select  $(\overline{CS})$ . Then Address (ADDR) settles and data appears on the output after time tAA, as at ① below.

Dataout is held for a short time (toH) after the address begins to change for the next access, as can be seen at ?——allowing addresses to begin to change early for the next cycle—then ambiguous data is on the bus until a new time tAA.

To avoid this noise on the bus and provide for longer output hold time, this device includes an output Read data latch which allows Read data to flow out while Output Latch Enable (OLE) is low, and then hold when OLE is high. Thus in the example below Read data at **3** is held until Read data at **3** is ready for output.

Note that Dataout is disabled (held low) by  $\overline{CS}$  high or  $\overline{WE}$  low, regardless of the state of the Output Latch.

#### **DESELECT TIMING**

Deselect timing is identical to a standard asynchronous device. This case occurs at  $\Theta$  below. Outputs attain the disable state (low) tRCs later Chip Select ( $\overline{\text{CS}}$ ) is taken to a high logic state. Status of other inputs do not effect the disabling of the device when chip select is de-asserted.

#### WRITE TIMING

Write cycles pipelined to allow easier design and higher system performance. The write pulse created on the WE input is used as a strobe to clock in the Write Address and Data into a register. This address and data are held in the register until the next write cycle, when they are used to write into the memory array through the Input Multiplexor.

Note the very short valid window required for Write Address and Data inputs. This is because these signals are captured by the input register. This means that input data may arrive late in the cycle, as at 40 below, or data and address may arrive late. as at 40 below.

DataOUT is disabled during the Write Cycle. If  $\overline{\text{CS}}$  is held low (active) and addresses remain unchanged, the DataOUT pins will output the written data after "Write Recovery Time" (twn), as for a standard asynchronous device.

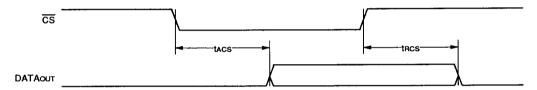
There is a special case when a Read cycle follows directly a Write Cycle to the same address. The memory array has not yet been updated with the Write data — it is still in the input register. This case is handled by including an address comparator and Output Multiplexor on the device: if the address being presented on the input pins is the same as the address stored in the input register, the data presented to the output pins is also from the input register.

## AC ELECTRICAL CHARACTERISTICS (Over the AC Operating Range)

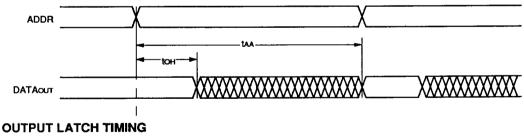
		10497S12 100497S12 Test 101497S12		1049 10049 10149			
Symbol	Parameter <sup>(1)</sup>	Condition	Min.	Max.	Min.	Max.	Unit
Read Cyck							
taa <sup>(2)</sup>	Address Access Time	- 1	-	12	-	15	ns
tacs	Chip Select Access Time	- 1	_	5	-	5	ns
trcs	Chip Select Recovery Time	-	_	5	-	<b>5</b>	ns
ton	Data Hold from Address Change		3	-		<b>.</b> -	ns
tolel	Latch Enable Low Pulse Width	- 1	5 🗞	1	5 🚲	-	ns
taho	Address Valid to OLE High	-	14		17	_	ns
tDH	Data Hold from Clock Low	1 - 1	0	-	0	_	ns
tor	Data Ready from Clock Low	-	0	4	0	4	ns
NOTES:	<u> </u>			<u> </u>			2774 tol

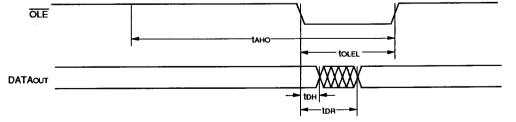
NOTES:

#### READ CYCLE GATED BY CHIP SELECT



#### **READ CYCLE GATED BY ADDRESS**





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<sup>1.</sup> Input and Output reference level is 50% point of waveform.

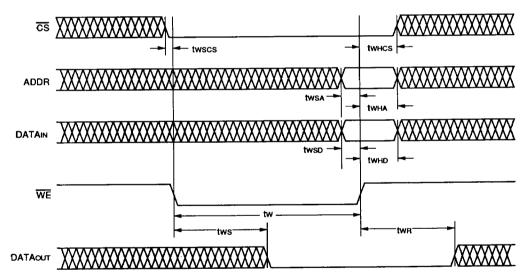
<sup>2.</sup> Read Data is valid at tAA or tAHO - tOLEL + tOR, whichever is larger; that is, Read Data is valid at the access time unless Output Latch Enable is high, and then access is ton after OLE goes low.

# AC ELECTRICAL CHARACTERISTICS (Over the AC Operating Range)

Symbol	Parameter <sup>(1)</sup>	Test Condition	10497S12 100497S12 101497S12		10497S15 100497S15 101497S15		
			Min.	Max.	Min.	Max.	Unit
Write Cycle							
tw	Write Pulse Width	_	10	-	12		ns
twscs	Setup Time for Chip Select	-	0	<u> </u>	1	<u> </u>	ns
twsa	Setup Time for Address	-	1	_	1 4	-	ns
twsp	Setup Time for Data In	_	1	<b>&gt;</b> -	1	» <u> </u>	ns
twics	Hold Time for Chip Select	-	2	* <b>-</b>	2	· _	ns
twha .	Hold Time for Address	-	2	-	2	_	ns
twHD	Hold Time for Data In	-	2	_	2	_	ns
tws	Write Disable Time		- 🤏	5	- 🦠	5	ns
twr	Write Recovery Time			5	-	5	ns
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NOTE:

## WRITE CYCLE TIMING DIAGRAM



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<sup>1.</sup> Input and Output reference level is 50% point of waveform.

#### ORDERING INFORMATION

